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BSI Standards Publication

**Electric components — Reliability —  
Reference conditions for failure rates  
and stress models for conversion**

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## National foreword

This British Standard is the UK implementation of EN 61709:2017. It is identical to IEC 61709:2017. It supersedes BS EN 61709:2011, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee DS/1, Dependability.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Electric components - Reliability - Reference conditions for  
failure rates and stress models for conversion  
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Composants électriques - Fiabilité - Conditions de référence  
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(IEC 61709:2017)

Bauelemente der Elektronik - Zuverlässigkeit -  
Referenzbedingungen für Ausfallraten und  
Beanspruchungsmodelle zur Umrechnung  
(IEC 61709:2017)

This European Standard was approved by CENELEC on 2017-03-24. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

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The text of document 56/1714/FDIS, future edition 3 of IEC 61709, prepared by IEC/TC 56 "Dependability" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61709:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-12-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-03-24

This document supersedes EN 61709:2011.

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The text of the International Standard IEC 61709:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60300-3-2:2004	NOTE	Harmonized as EN 60300-3-2:2005.
IEC 60300-3-3	NOTE	Harmonized as EN 60300-3-3.
IEC 60721 (series)	NOTE	Harmonized as EN 60721 (series).
IEC 60721-3-3	NOTE	Harmonized as EN 60721-3-3.
IEC 60721-3-4	NOTE	Harmonized as EN 60721-3-4.
IEC 60721-3-5	NOTE	Harmonized as EN 60721-3-5.
IEC 60721-3-7	NOTE	Harmonized as EN 60721-3-7.
IEC 61014:2003	NOTE	Harmonized as EN 61014:2003.
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IEC 61360-1:2009	NOTE	Harmonized as EN 61360-1:2010.
IEC 61360-4:2005	NOTE	Harmonized as EN 61360-4:2005.
IEC 61508 (series)	NOTE	Harmonized as EN 61508 (series).
IEC 61649:2008	NOTE	Harmonized as EN 61649:2008.
IEC 61703:2002	NOTE	Harmonized as EN 61703:2002.
IEC 61710	NOTE	Harmonized as EN 61710.

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IEC 62007 (series)	NOTE	Harmonized as EN 62007 (series).
IEC 62741	NOTE	Harmonized as EN 62741.
IEC 62308:2006	NOTE	Harmonized as EN 62308:2006.

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**Annex ZA**  
(normative)

**Normative references to international publications  
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-192	2015	International electrotechnical vocabulary - Part 192: Dependability	-	-

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## CONTENTS

FOREWORD.....	9
INTRODUCTION.....	11
1 Scope.....	12
2 Normative references .....	12
3 Terms, definitions and symbols .....	12
3.1 Terms and definitions.....	12
3.2 Symbols.....	16
4 Context and conditions .....	17
4.1 Failure modes and mechanisms.....	17
4.2 Thermal modelling .....	18
4.3 Mission profile consideration.....	18
4.3.1 General .....	18
4.3.2 Operating and non-operating conditions .....	18
4.3.3 Dormancy .....	19
4.3.4 Storage .....	19
4.4 Environmental conditions .....	19
4.5 Components choice .....	21
4.6 Reliability growth during the deployment phase of new equipment .....	22
4.7 How to use this document.....	23
5 Generic reference conditions and stress models.....	24
5.1 Recommended generic reference conditions.....	24
5.2 Generic stress models .....	25
5.2.1 General .....	25
5.2.2 Stress factor for voltage dependence, $\pi_U$ .....	26
5.2.3 Stress factor for current dependence, $\pi_I$ .....	26
5.2.4 Stress factor for temperature dependence, $\pi_T$ .....	26
5.2.5 Environmental application factor, $\pi_E$ .....	28
5.2.6 Dependence on switching rate, $\pi_S$ .....	28
5.2.7 Dependence on electrical stress, $\pi_{ES}$ .....	29
5.2.8 Other factors of influence .....	29
6 Integrated semiconductor circuits .....	29
6.1 Specific reference conditions .....	29
6.2 Specific stress models .....	31
6.2.1 General .....	31
6.2.2 Voltage dependence, factor $\pi_U$ .....	32
6.2.3 Temperature dependence, factor $\pi_T$ .....	32
7 Discrete semiconductors .....	35
7.1 Specific reference conditions .....	35
7.2 Specific stress models .....	36
7.2.1 General .....	36
7.2.2 Voltage dependence for transistors, factor $\pi_U$ .....	37
7.2.3 Temperature dependence, factor $\pi_T$ .....	37
8 Optoelectronic components .....	39

This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

8.1	Specific reference conditions .....	39
8.2	Specific stress models .....	41
8.2.1	General .....	41
8.2.2	Voltage dependence, factor $\pi_U$ .....	41
8.2.3	Current dependence, factor $\pi_I$ .....	41
8.2.4	Temperature dependence, factor $\pi_T$ .....	42
9	Capacitors .....	44
9.1	Specific reference conditions .....	44
9.2	Specific stress model .....	44
9.2.1	General .....	44
9.2.2	Voltage dependence, factor $\pi_U$ .....	44
9.2.3	Temperature dependence, factor $\pi_T$ .....	46
10	Resistors and resistor networks .....	47
10.1	Specific reference conditions .....	47
10.2	Specific stress models .....	48
10.2.1	General .....	48
10.2.2	Temperature dependence, factor $\pi_T$ .....	48
11	Inductors, transformers and coils .....	49
11.1	Reference conditions .....	49
11.2	Specific stress model .....	49
11.2.1	General .....	49
11.2.2	Temperature dependence, factor $\pi_T$ .....	49
12	Microwave devices .....	50
12.1	Specific reference conditions .....	50
12.2	Specific stress models .....	51
13	Other passive components .....	51
13.1	Specific reference conditions .....	51
13.2	Specific stress models .....	51
14	Electrical connections .....	51
14.1	Specific reference conditions .....	51
14.2	Specific stress models .....	52
15	Connectors and sockets .....	52
15.1	Reference conditions .....	52
15.2	Specific stress models .....	52
16	Relays .....	52
16.1	Reference conditions .....	52
16.2	Specific stress models .....	53
16.2.1	General .....	53
16.2.2	Dependence on switching rate, factor $\pi_S$ .....	53
16.2.3	Dependence on electrical stress, factor $\pi_{ES}$ .....	54
16.2.4	Temperature dependence, factor $\pi_T$ .....	55
17	Switches and push-buttons .....	55
17.1	Specific reference conditions .....	55
17.2	Specific stress model .....	56
17.2.1	General .....	56



This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

17.2.2	Dependence on electrical stress, factor $\pi_{ES}$	56
18	Signal and pilot lamps	57
18.1	Specific reference conditions	57
18.2	Specific stress model	57
18.2.1	General	57
18.2.2	Voltage dependence, factor $\pi_U$	58
19	Printed circuit boards (PCB)	58
20	Hybrid circuits	58
Annex A (normative)	Failure modes of components	59
Annex B (informative)	Thermal model for semiconductors	62
B.1	Thermal model	62
B.2	Junction temperature calculation	63
B.3	Thermal resistance evaluation	64
B.4	Power dissipation of an integrated circuit $P$	65
Annex C (informative)	Failure rate prediction	68
C.1	General	68
C.2	Failure rate prediction for assemblies	68
C.2.1	General	68
C.2.2	Assumptions and limitations	69
C.2.3	Process for failure rate prediction	69
C.2.4	Prediction models	70
C.2.5	Other methods of reliability prediction	71
C.2.6	Validity considerations of reliability models and predictions	72
C.3	Component considerations	73
C.3.1	Component model	73
C.3.2	Components classification	73
C.4	General consideration about failure rate	73
C.4.1	General	73
C.4.2	General behaviour of the failure rate of components	74
C.4.3	Expected values of failure rate	75
C.4.4	Sources of variation in failure rates	75
Annex D (informative)	Considerations on mission profile	77
D.1	General	77
D.2	Dormancy	77
D.3	Mission profile	78
D.4	Example of mission profile	79
Annex E (informative)	Useful life models	80
E.1	General	80
E.2	Power transistors	80
E.3	Optocouplers	80
E.3.1	Useful life $L$	80
E.3.2	Factor $L_0$	81
E.3.3	Factor $\kappa_0$	81
E.3.4	Factor $\kappa_1$	82
E.3.5	Factor $\kappa_2$	82
E.3.6	Factor $\kappa_3$	82
E.4	LED and LED modules	83

This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

E.4.1	Useful life $L$ .....	83
E.4.2	Factor $L_0$ .....	83
E.4.3	Factor $\kappa_0$ .....	84
E.4.4	Factor $\kappa_1$ .....	84
E.4.5	Factor $\kappa_2$ .....	85
E.4.6	Factor $\kappa_3$ .....	85
E.5	Aluminium, non-solid electrolyte capacitors .....	85
E.6	Relays .....	86
E.7	Switches and keyboards .....	86
E.8	Connectors .....	86
Annex F (informative)	Physics of failure .....	87
F.1	General .....	87
F.2	Failure mechanisms of integrated circuits .....	88
Annex G (informative)	Considerations for the design of a data base on failure rates .....	89
G.1	General .....	89
G.2	Data collection acquisition – collection process .....	89
G.3	Which data to collect and how to collect it .....	89
G.4	Calculation and decision making .....	90
G.5	Data descriptions .....	90
G.6	Identification of components .....	90
G.6.1	General .....	90
G.6.2	Component identification .....	91
G.6.3	Component technology .....	91
G.7	Specification of components .....	91
G.7.1	General .....	91
G.7.2	Electrical specification of components .....	91
G.7.3	Environmental specification of components .....	92
G.8	Field related issues data .....	92
G.8.1	General .....	92
G.8.2	Actual field conditions .....	92
G.8.3	Data on field failures .....	92
G.9	Test related issues data .....	93
G.9.1	General .....	93
G.9.2	Actual test conditions .....	93
G.9.3	Data on test failures .....	93
G.10	Failure rate database attributes .....	94
Annex H (informative)	Potential sources of failure rate data and methods of selection .....	96
H.1	General .....	96
H.2	Data source selection .....	96
H.3	User data .....	97
H.4	Manufacturer's data .....	97
H.5	Handbook reliability data .....	98
H.5.1	General .....	98
H.5.2	Using handbook data with this document .....	98
H.5.3	List of available handbooks .....	99
Annex I (informative)	Overview of component classification .....	102
I.1	General .....	102
I.2	The IEC 61360 system .....	102

This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

I.3	Other systems.....	110
I.3.1	General .....	110
I.3.2	NATO stock numbers.....	110
I.3.3	UNSPSC codes .....	110
I.3.4	STEP/EXPRESS.....	110
I.3.5	IECQ .....	110
I.3.6	ECALS .....	111
I.3.7	ISO 13584 .....	111
I.3.8	MIL specifications.....	111
Annex J (informative)	Presentation of component reliability data.....	112
J.1	General.....	112
J.2	Identification of components .....	112
J.2.1	General .....	112
J.2.2	Component identification .....	113
J.2.3	Component technology .....	113
J.3	Specification of components .....	113
J.3.1	General .....	113
J.3.2	Electrical specification of components .....	113
J.3.3	Environmental specification of components .....	113
J.4	Test related issues data.....	113
J.4.1	General .....	113
J.4.2	Actual test conditions .....	114
J.5	Data on test failures.....	114
Annex K (informative)	Examples .....	116
K.1	Integrated circuit.....	116
K.2	Transistor .....	116
K.3	Capacitor .....	116
K.4	Relay.....	117
Bibliography.....		118
Figure 1	– Comparison of the temperature dependence of $\pi_T$ for CMOS IC.....	24
Figure 2	– Selection of stress regions in accordance with current and voltage-operating conditions .....	54
Figure 3	– Selection of stress regions in accordance with current and voltage-operating conditions .....	56
Figure B.1	– Temperatures inside equipment.....	63
Figure B.2	– Thermal resistance model.....	64
Figure D.1	– Mission profile .....	79
Table 1	– Basic environments .....	20
Table 2	– Values of environmental parameters for basic environments .....	21
Table 3	– Recommended reference conditions for environmental and mechanical stresses.....	25
Table 4	– Environmental application factor, $\pi_E$ .....	28
Table 5	– Memory.....	30
Table 6	– Microprocessors and peripherals, microcontrollers and signal processors .....	30
Table 7	– Digital logic families and bus interfaces, bus driver and receiver circuits .....	30

This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

Table 8 – Analog ICs .....	31
Table 9 – Application-specific ICs (ASICs) .....	31
Table 10 – Constants for voltage dependence .....	32
Table 11 – Factor $\pi_U$ for digital CMOS-family ICs .....	32
Table 12 – Factor $\pi_U$ for bipolar analog ICs .....	32
Table 13 – Constants for temperature dependence .....	32
Table 14 – Factor $\pi_T$ for ICs (without EPROM; FLASH-EPROM; OTPROM; EEPROM; EAROM) .....	34
Table 15 – Factor $\pi_T$ for EPROM; FLASH-EPROM; OTPROM; EEPROM; EAROM .....	34
Table 16 – Transistors common, low frequency .....	35
Table 17 – Transistors, microwave, (e.g. RF > 800 MHz) .....	35
Table 18 – Diodes .....	36
Table 19 – Power semiconductors .....	36
Table 20 – Constants for voltage dependence of transistors .....	37
Table 21 – Factor $\pi_U$ for transistors .....	37
Table 22 – Constants for temperature dependence of discrete semiconductors .....	37
Table 23 – Factor $\pi_T$ for transistors, reference and microwave diodes .....	38
Table 24 – Factor $\pi_T$ for diodes (without reference and microwave diodes) and power semiconductors .....	38
Table 25 – Optoelectronic semiconductor signal receivers .....	39
Table 26 – LEDs, IREDS, laser diodes and transmitter components .....	39
Table 27 – Optocouplers and light barriers .....	40
Table 28 – Passive optical components .....	40
Table 29 – Transceiver, transponder and optical sub-equipment .....	40
Table 30 – Constants for voltage dependence of phototransistors .....	41
Table 31 – Factor $\pi_U$ for phototransistors .....	41
Table 32 – Constants for current dependence of LEDs and IREDS .....	42
Table 33 – Factor $\pi_I$ for LEDs and IREDS .....	42
Table 34 – Constants for temperature dependence of optoelectronic components .....	42
Table 35 – Factor $\pi_T$ for optical components .....	43
Table 36 – Capacitors .....	44
Table 37 – Constants for voltage dependence of capacitors .....	45
Table 38 – Factor $\pi_U$ for capacitors .....	45
Table 39 – Constants for temperature dependence of capacitors .....	46
Table 40 – Factor $\pi_T$ for capacitors .....	47
Table 41 – Resistors and resistor networks .....	48
Table 42 – Constants for temperature dependence of resistors .....	48
Table 43 – Factor $\pi_T$ for resistors .....	49
Table 44 – Inductors, transformers and coils .....	49
Table 45 – Constants for temperature dependence of inductors, transformers and coils .....	49
Table 46 – Factor $\pi_T$ for inductors, transformers and coils .....	50

This is a preview of "BS EN 61709:2017". [Click here to purchase the full version from the ANSI store.](#)

Table 47 – Microwave devices .....	50
Table 48 – Other passive components .....	51
Table 49 – Electrical connections.....	52
Table 50 – Connectors and sockets .....	52
Table 51 – Relays.....	53
Table 52 – Factor $\pi_{ES}$ for low current relays .....	54
Table 53 – Factor $\pi_{ES}$ for general purpose relays .....	54
Table 54 – Factor $\pi_{ES}$ for automotive relays.....	55
Table 55 – Constants for temperature dependence of relays.....	55
Table 56 – Factor $\pi_T$ for relays .....	55
Table 57 – Switches and push-buttons.....	56
Table 58 – Factor $\pi_{ES}$ for switches and push-buttons for low electrical stress.....	57
Table 59 – Factor $\pi_{ES}$ for switches and push-buttons for higher electrical stress .....	57
Table 60 – Signal and pilot lamps .....	57
Table 61 – Factor $\pi_U$ for signal and pilot lamps.....	58
Table A.1 – Failure modes: ICs (digital) .....	59
Table A.2 – Failure modes: transistors, diodes, optocouplers.....	60
Table A.3 – Failure modes: LEDs.....	60
Table A.4 – Failure modes: laser diodes and modules .....	60
Table A.5 – Failure modes: photodiodes and receiver modules .....	60
Table A.6 – Failure modes: capacitors .....	61
Table A.7 – Failure modes: resistors, inductive devices, relays.....	61
Table B.1 – Thermal resistance as a function of package type, pin number and airflow factor .....	65
Table B.2 – Typical values of $\nu$ are $K$ .....	65
Table B.3 – Values of $P_{DC}$ and $P_f$ .....	66
Table E.1 – Useful life limitations for switches and keyboards.....	86
Table F.1 – Failure mechanism for Integrated circuits .....	88
Table G.1 – Reliability prediction database attributes.....	95
Table H.1 – Result of calculation for transistors common, low frequency.....	99
Table H.2 – Sources of reliability data (in alphabetical order).....	99
Table I.1 – Classification tree (IEC 61360-4).....	103

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

# **ELECTRIC COMPONENTS – RELIABILITY – REFERENCE CONDITIONS FOR FAILURE RATES AND STRESS MODELS FOR CONVERSION**

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 61709 has been prepared by IEC technical committee 56: Dependability.

This third edition cancels and replaces the second edition, published in 2011. This edition constitutes a technical revision. This third edition is a merger of IEC 61709:2011 and IEC TR 62380:2004.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of 4.5 Components choice, 4.6 Reliability growth during the deployment phase of new equipment, 4.7 How to use this document, and of Clause 19 Printed circuit boards (PCB) and Clause 20 Hybrid circuits with respect to IEC TR 62380;
- b) addition of failure modes of components in Annex A;

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- c) modification of Annex B, Thermal model for semiconductors, adopted and revised from IEC TR 62380;
- d) modification of Annex D, Considerations on mission profile;
- e) modification of Annex E, Useful life models, adopted and revised from IEC TR 62380;
- f) revision of Annex F (former B.2.6.4), Physics of failure;
- g) addition of Annex G (former Annex C), Considerations for the design of a data base on failure rates, complemented with parts of IEC 60319;
- h) addition of Annex H, Potential sources of failure rate data and methods of selection;
- i) addition of Annex J, Presentation of component reliability data, based on IEC 60319.

The text of this standard is based on the following documents:

FDIS	Report on voting
56/1714/FDIS	56/1721/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

**IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

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## INTRODUCTION

This document is intended for the reliability prediction of electric components as used in equipment and is aimed at organizations that have their own data and describes how to state and use that data in order to perform reliability predictions.

It can also be used to allow an organization to set up a failure rate database and describes the reference conditions for which field failure rates should be stated. The reference conditions adopted in this document are typical of the majority of applications of components in equipment however when components operate under other conditions the users may consider stating these conditions as their reference conditions.

Using the presented stress models allows extrapolation of failure rates from reference conditions to other operating conditions which in turn permits the prediction of failure rates at assembly level. This allows estimation of the effect of design changes or changes in the environmental conditions on component reliability. Reliability prediction is most useful in the early design phase of equipment. It can be used, for example, to identify potential reliability problems, the planning of logistic support strategies and the evaluation of designs.

The stress models contained herein are generic and are as simple as possible while still being comparable with more complex equations contained in other models. The predictions generated using this document have a wide range of prediction accuracy.

This document does not contain failure rates, but it describes how they can be stated and used. This approach allows a user to select the most relevant and up to date failure rates for the prediction from a source that they select. This document also contains information on how to select the data that can be used in the presented models.

The failure rates considered in this document are assumed to be constant, either for an unlimited period of operation (general case) or for limited periods. The limitation of life is called useful life and applies only for some few component families, reaching the wear-out failure period (during which the failure rate is increasing) within the normal period of use. It is hence assumed that during useful life, the failure rate can be considered constant for any practical use.

For the purposes of this document the term electric component includes the commonly used terms "electronic component", "electrical component" and "electro-mechanical component".



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# **ELECTRIC COMPONENTS – RELIABILITY – REFERENCE CONDITIONS FOR FAILURE RATES AND STRESS MODELS FOR CONVERSION**

## **1 Scope**

This document gives guidance on the use of failure rate data for reliability prediction of electric components used in equipment.

The method presented in this document uses the concept of reference conditions which are the typical values of stresses that are observed by components in the majority of applications.

Reference conditions are useful since they provide a known standard basis from which failure rates can be modified to account for differences in environment from the environments taken as reference conditions. Each user can use the reference conditions defined in this document or use their own. When failure rates stated at reference conditions are used it allows realistic reliability predictions to be made in the early design phase.

The stress models described herein are generic and can be used as a basis for conversion of failure rate data given at these reference conditions to actual operating conditions when needed and this simplifies the prediction approach. Conversion of failure rate data is only possible within the specified functional limits of the components.

This document also gives guidance on how a database of component failure data can be constructed to provide failure rates that can be used with the included stress models. Reference conditions for failure rate data are specified, so that data from different sources can be compared on a uniform basis. If failure rate data are given in accordance with this document then additional information on the specified conditions can be dispensed with.

This document does not provide base failure rates for components – rather it provides models that allow failure rates obtained by other means to be converted from one operating condition to another operating condition.

The prediction methodology described in this document assumes that the parts are being used within its useful life. The methods in this document have a general application but are specifically applied to a selection of component types as defined in Clauses 6 to 20 and I.2.

## **2 Normative references**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-192:2015, *International electrotechnical vocabulary – Part 192: Dependability*

## **3 Terms, definitions and symbols**

### **3.1 Terms and definitions**

For the purposes of this document, the terms and definitions given in IEC 60050-192 and the following apply.